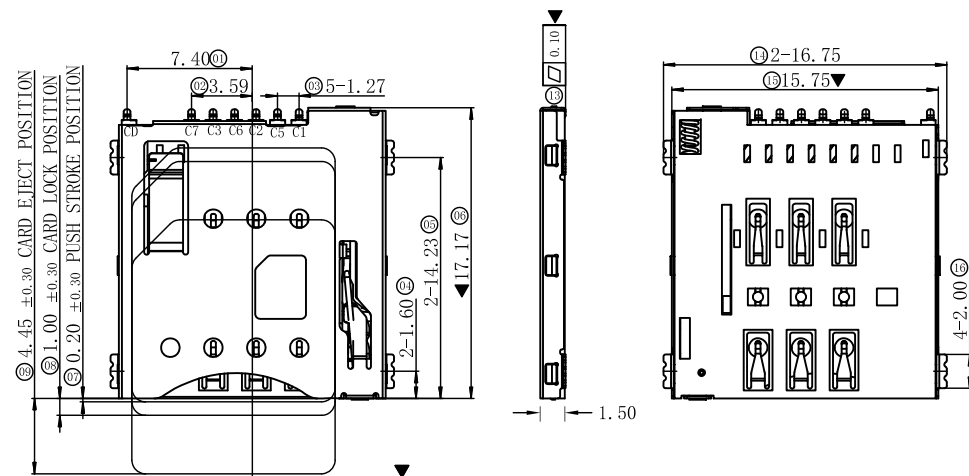


NOTES:

1. MATERIAL:

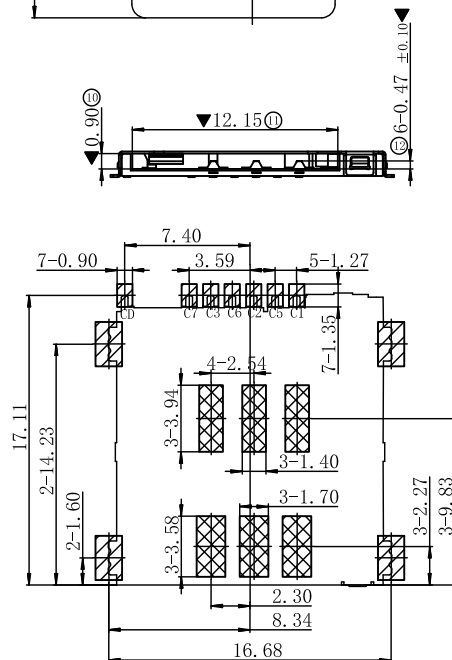
HOUSING:HighTemperatureThermoplastic
Terminal:CopperAlloy
Shell:StainlessSteel

2. PLATING:

Terminal:50u"NiUNDERPLATEDOVERALL
G/FPLATEDONCONTACTAREA
G/FPLATEDONSOLDERAREA
Sheel:30u"NiUNDERPLATEDOVERALL
G/FPLATEDONCONTACTAREAANDSOLDERAREA

3. TECHNICALSPECIALITY:

RATEDVOLTAGE:30VACMAX.
CURRENTRATING:0.5AMAX.
INSULATIONRESISTANCE:1000MΩ MIN
CONTACTREISTANCE:50MΩ MAX
WITHSTANDINGVOLTAGE:500VACFOR1MINUTES
OPERATINGTEMPERATURE:-40℃~+85℃ Humidity80%R.HMAX



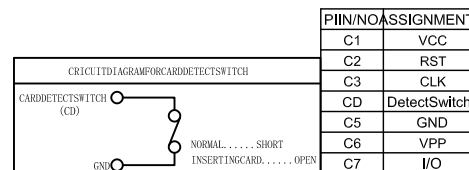
RECOMMENDEDPCBLAYOUT

TOLERANCE: ± 0.05

SMTSOLDERAREA

COPPERRESTRICTEDAREA

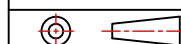
1. TOUCHAREAOFFCONTACT TIPSNOELECTRICALFUNCTION
2. NOFIRSTPCB_LAYOUT CIRCUITSINTHEAREA



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ± 0.30
X.XX ± 0.25
X.XXX ± 0.15

X' $\pm 2^\circ$ X.X' $\pm 0.5^\circ$ 

UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

MICRO SIM PUSH 6+1P 1.5H

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCW277-SIM07-150B

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-SIM2103261704

SHEET NO.

1 OF 1